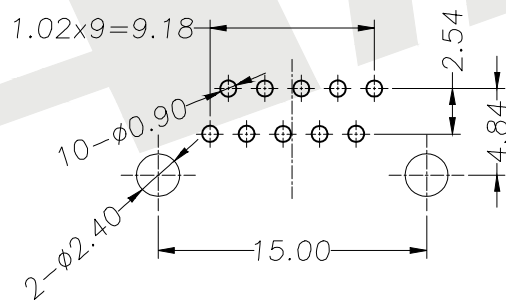
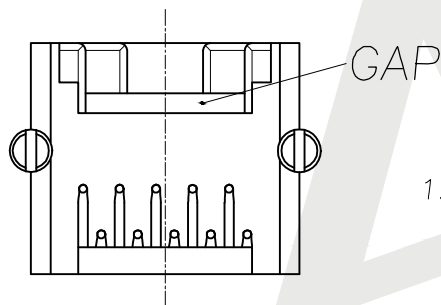
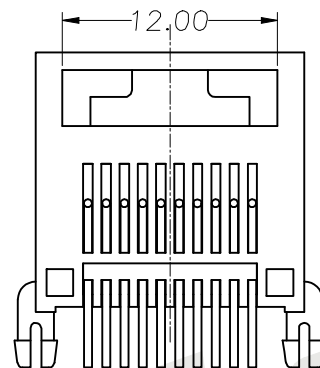
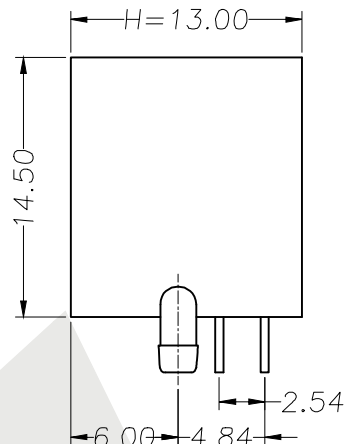
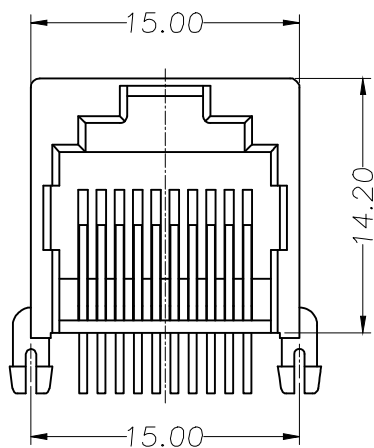


HSF



PC Board Layout

NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE  $t=0.3\text{mm}$
3. PLATING: SELECTING GOLD PLATING  $1\mu \sim 50\mu$  OVER NICKEL IN CONTACT AREA.  $150\mu$  TIN PLATIN. OVER NICKEL IN SOLDER AREA

4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE ELECTRICAL

1. VOLTAGE RATING: 125VAC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30MILLIOHMS MAX
4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTTON PRB-SOLDER: 1 LB MIN

REVRONMENTAL

1. STORAGE:  $-40^{\circ}\text{C}$  TO  $85^{\circ}\text{C}$
2. OPERATION:  $0^{\circ}\text{C}$  TO  $70^{\circ}\text{C}$

Order code:

ATRJ5521 - 10P - 10C - X - A - X  
 ① ② ③ ④ ⑤ ⑥

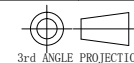
- ① SERIES NO:
- ② NUMBER OF POSITIONS (8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (8C, 6C, 4C)
- ④ Contact Plating  
 G0: Gold flash  
 G1: 3U" Gold  
 G2: 5U" Gold  
 G3: 10U" Gold  
 G4: 15U" Gold  
 G5: 30U" Gold  
 SN: Tin
- ⑤ Shield  
 A: W/O Shield  
 B: Half Shield  
 C: Shield W/Eml  
 D: Shield W/O Eml
- ⑥ Ports  
 A: 1X1P  
 B: 1X2P  
 C: 1X4P  
 D: 1X5P  
 E: 1X6P  
 F: 1X8P

Unless Otherwise specified tolerance  
 X.  $\pm 0.35$  X.XX:  $\pm 0.20$   
 X.X:  $\pm 0.25$  X.XXX:  $\pm 0.15$

**Antenk**® ANTENK ELECTRONICS CO., LTD  
[Http://www.antenk.com](http://www.antenk.com)  
 E-mail: sales@antenk.com

SCALE: As Shown UNIT: mm  
 DRAW Wu Feng Rong DATE 06/09/2019  
 CHECK BobYang DATE 06/09/2019

TITLE: RJ45 Jack side entry, 1X1P, Full Plastic



DRAWING NO: ATRJ5521-10P10C-X-A-X  
 PRODUCT NO: ATRJ5521-10P10C-X-A-X

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		